

What is claimed is:

1. A circuit module comprising:
  - a plurality of bus bars arranged approximately in a same plane to form a power circuit;
  - a control circuit board in which a control circuit for controlling electrical continuity of the power circuit is built, being bonded to said bus bars, and provided with a conductor segment to be electrically connected to at least a specific one of said bus bars on one surface of said control circuit board on the opposite side of the other surface bonded to said bus bars, and a through-hole penetrating a main body of the control circuit board at a position adjacent to said conductor segment so as to expose a portion of said specific bus bar; and
    - an electrically-connecting member of a shape bridging between said through-hole and said conductor segment, said electrically-connecting member being soldered onto both said conductor segment and the exposed portion of said specific bus bar.
2. The circuit module as defined in claim 1, wherein said electrically-connecting member is formed of a metal plate, and disposed in a posture approximately parallel to said control circuit board.
3. The circuit module as defined in claim 2, wherein said electrically-connecting member has a surface soldered onto said conductor segment and a surface soldered onto the exposed portion of said specific bus bar, and is formed with a step portion providing a height difference approximately equal to a board thickness of said control circuit board, between the surfaces.
4. The circuit module as defined in either one of claims 1 to 3, wherein said electrically-connecting member is formed with a cutout in at least one of the portion soldered onto said conductor segment and the portion soldered onto the exposed portion of said specific bus bar.
5. The circuit module as defined in either one of claims 1 to 4, wherein said control circuit

board is provided with a plurality of said through-holes adjacent to said conductor segment, and said electrically-connecting member formed in a shape bridging over said through-holes and said conductor segment is soldered onto said conductor segment and a specific one or more of said bus bars exposed through said through-holes.

6. The circuit module as defined in claim 5, wherein said through-holes are formed at the both sides of and across said conductor segment, while said electrically-connecting member is formed in a plate shape bridging over said through-holes and said conductor segment and has an intermediate portion soldered onto said conductor segment and opposite end portions each soldered onto a corresponding one or more of the exposed portions of said specific one or more bus bars.